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FAIRCHILD SEMICONDUCTOR®

2014 年 1 月

FDP100N10

N 沟道 PowerTrench® MOSFET

100 V， 75 A， 10 mΩ

特性

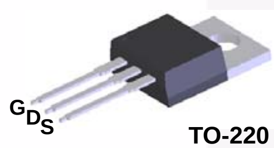
- $R_{DS(on)}$ = 8.2 mΩ (Typ.)@V_{GS} = 10 V, I_D = 75 A
- 快速开关速度
- 低栅极电荷
- 高性能沟道技术可实现极低的 $R_{DS(on)}$
- 高功率和高电流处理能力
- 符合 RoHS 标准

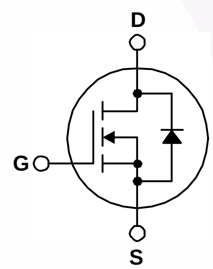
说明

此 N 沟道 MOSFET 采用飞兆半导体先进的 PowerTrench® 工艺生产，这一先进工艺是专为最大限度地降低通态电阻并保持卓越开关性能而定制的。

应用

- 用于 ATX/ 服务器 / 通信 PSU 的同步整流
- 电池保护电路
- 电机驱动和不间断电源
- 微型光伏逆变器





MOSFET 最大额定值 T_C =25°C 除非另有说明。

符号	参数		FDP100N10	单位
V_{DSS}	漏极—源极电压		100	V
V_{GSS}	栅极—源极电压		±20	V
I_D	漏极电流	- 连续 (T_C=75°C)	75	A
I_{DM}	漏极电流	- 脉冲 （说明 1）	300	A
E_{AS}	单脉冲雪崩能量 （说明 2）		365	mJ
dv/dt	峰值二极管恢复 dv/dt （说明 3）		6	V/ns
P_D	功耗	(T_C = 25°C)	208	W
		- 降额 25°C 以上	1.4	W/°C
T_J, T_{STG}	工作和存储温度范围		-55 至 +175	°C
T_L	用于焊接的最大引脚温度，距离外壳 1/8"，持续 5 秒		300	°C

热性能

符号	参数	FDP100N10	单位
$R_{\theta JC}$	结至外壳热阻最大值	0.72	°C/W
$R_{\theta JA}$	结至环境热阻最大值	62.5	

封装标识与定购信息

器件编号	顶标	封装	包装方法	卷尺寸	带宽	数量
FDP100N10	FDP100N10	TO-220	塑料管	不适用	不适用	50 个

电气特性 T_C =25°C 除非另有说明。

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV_{DSS}	漏极—源极击穿电压	I_D = 250 µA, V_{GS} = 0 V, T_J = 25°C	100	-	-	V
ΔBV_{DSS} / ΔT_J	击穿电压温度系数	I_D = 250 µA，参考条件是 25°C	-	0.1	-	V/°C
I_{DSS}	零栅极电压漏极电流	V_{DS} = 100 V, V_{GS} = 0 V	-	-	1	µA
		V_{DS} = 100 V, V_{GS} = 0 V, T_J = 150°C	-	-	500	µA
I_{GSS}	栅极 - 体漏电流	V_{GS} = ±20 V, V_{DS} = 0 V	-	-	±100	nA
导通特性						
$V_{GS(th)}$	栅极阈值电压	V_{GS} = V_{DS}, I_D = 250 µA	2.5	-	4.5	V
$R_{DS(on)}$	漏极至源极静态导通电阻	V_{GS} = 10 V, I_D = 75 A	-	8.2	10	mΩ
g_{FS}	正向跨导	V_{DS} = 10 V, I_D = 37.5 A	-	110	-	S
动态特性						
C_{iss}	输入电容	V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz	-	5500	7300	pF
C_{oss}	输出电容		-	530	710	pF
C_{rss}	反向传输电容		-	220	325	pF
$Q_{g(tot)}$	10V 的栅极电荷总量	V_{DS} = 50 V, I_D = 75 A, V_{GS} = 10 V （说明 4）	-	76	100	nC
Q_{gs}	栅极 - 源极栅极电荷		-	30	-	nC
Q_{gd}	栅漏极“米勒”电荷		-	20	-	nC
开关特性						
$t_{d(on)}$	导通延迟时间	V_{DD} = 50 V, I_D = 75 A, V_{GS} = 10 V, R_G = 25 Ω （说明 4）	-	70	150	ns
t_r	开通上升时间		-	265	540	ns
$t_{d(off)}$	关断延迟时间		-	125	260	ns
t_f	关断下降时间		-	115	240	ns
漏源极二极管特性						
I_S	漏源极二极管最大正向连续电流		-	-	75	A
I_{SM}	漏源极二极管最大正向脉冲电流		-	-	300	A
V_{SD}	漏源极二极管正向电压	V_{GS} = 0 V, I_{SD} = 75 A	-	-	1.25	V
t_{rr}	反向恢复时间	V_{GS} = 0 V, I_{SD} = 75 A, dI_F/dt = 100 A/µs	-	71	-	ns
Q_{rr}	反向恢复电荷		-	164	-	nC

注意：

1: 重复额定值：脉冲宽度受限于最大结温。

2: L = 0.13 mH, I_{AS} = 75 A, V_{DD} = 25 V, R_G = 25 Ω，启动 = 25°C。

3: I_{SD} ≤ 75 A, di/dt ≤ 200 A/µs, V_{DD} ≤ BV_{DSS}，开始 T_J=25°C。

4: 本质上独立于工作温度的典型特性。

典型性能特征

图 **1.** 导通区域特性

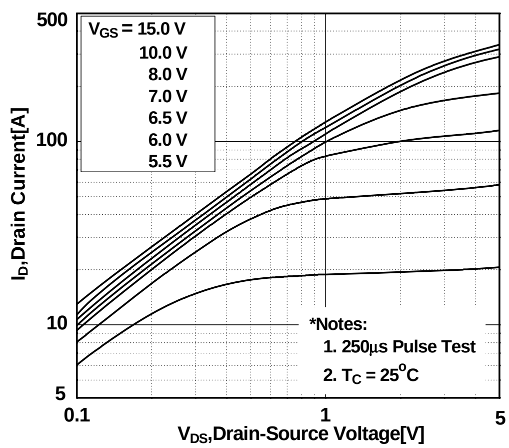


图 **2.** 传输特性

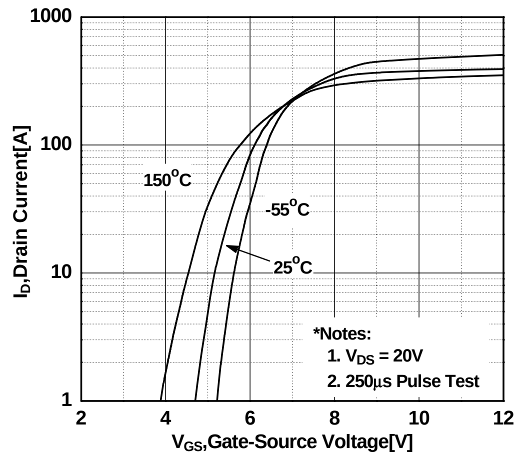


图 **3.** 导通电阻变量与漏极电流和栅极电压的关系

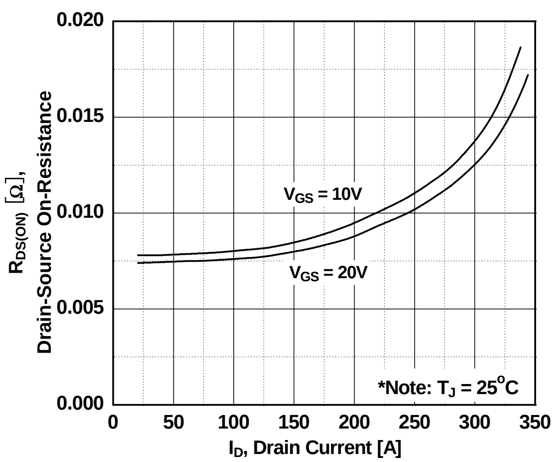


图 **4.** 体二极管正向电压变量与源电流的关系和温度

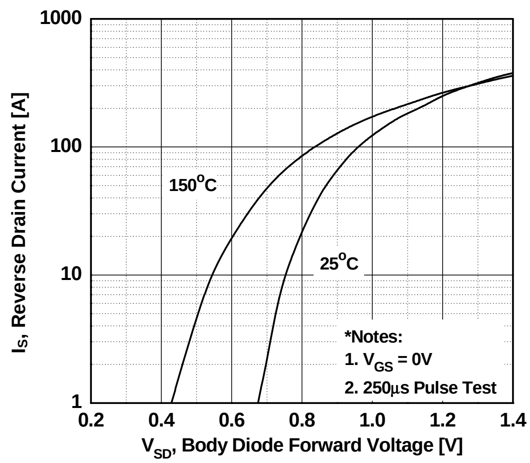


图 **5.** 电容特性

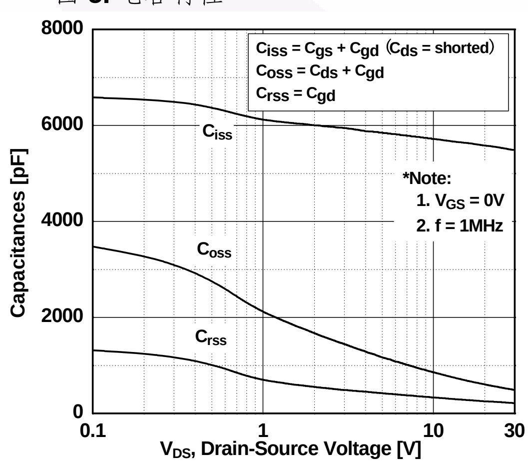
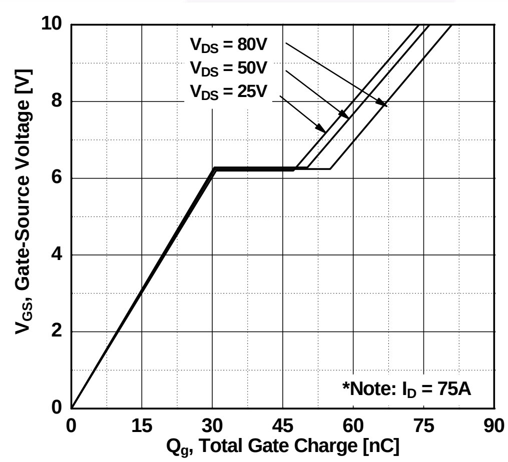


图 **6.** 栅极电荷特性



典型性能特征（接上页）

图 **7.** 击穿电压变量与温度的关系

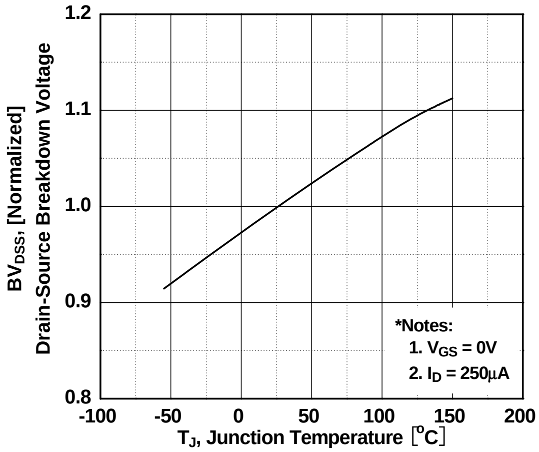


图 **8.** 导通电阻变量与温度的关系

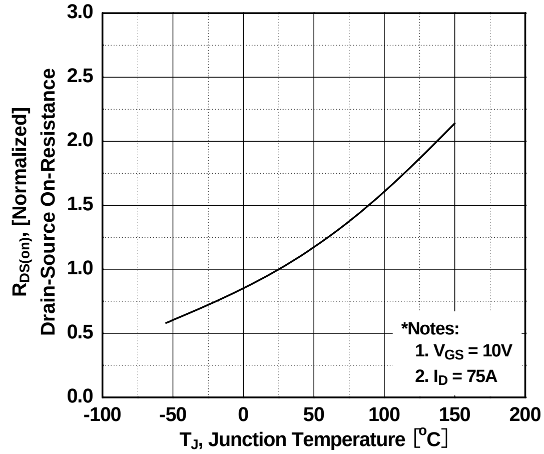


图 **9.** 最大安全工作区

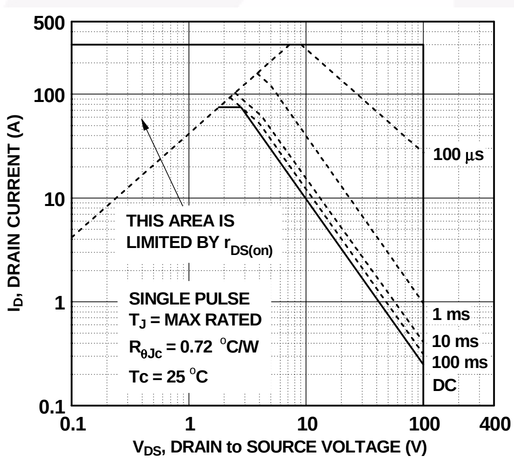


图 **10.** 最大漏极电流与壳体温度的关系

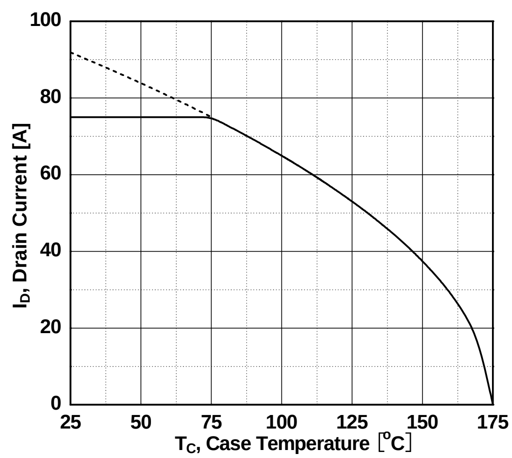
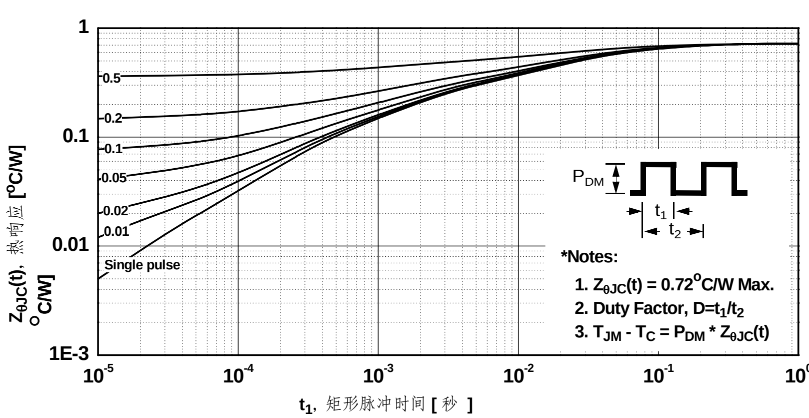


图 **11.** 瞬态热响应曲线



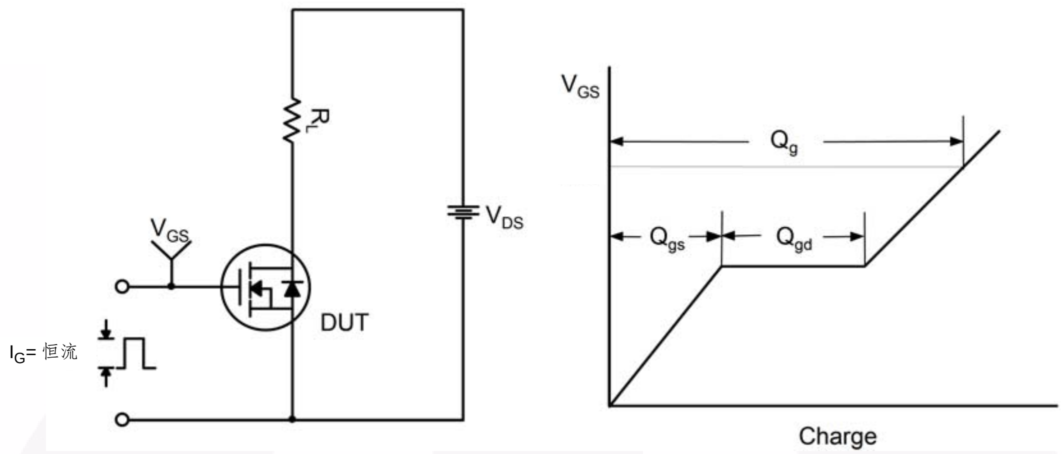


图 **12.** 栅极电荷测试电路与波形

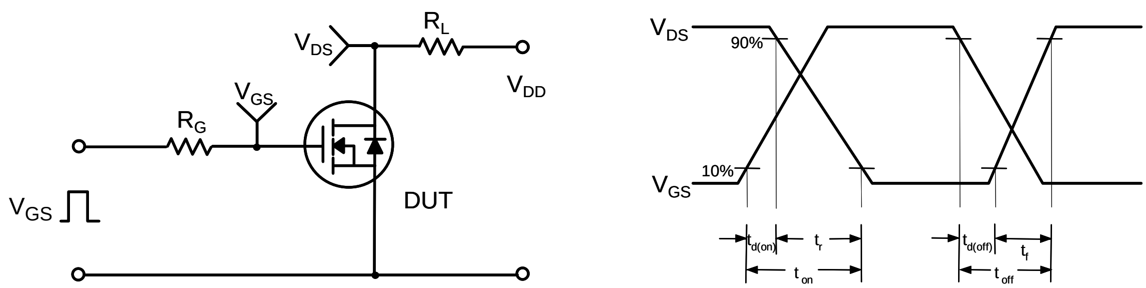


图 **13.** 阻性开关测试电路与波形

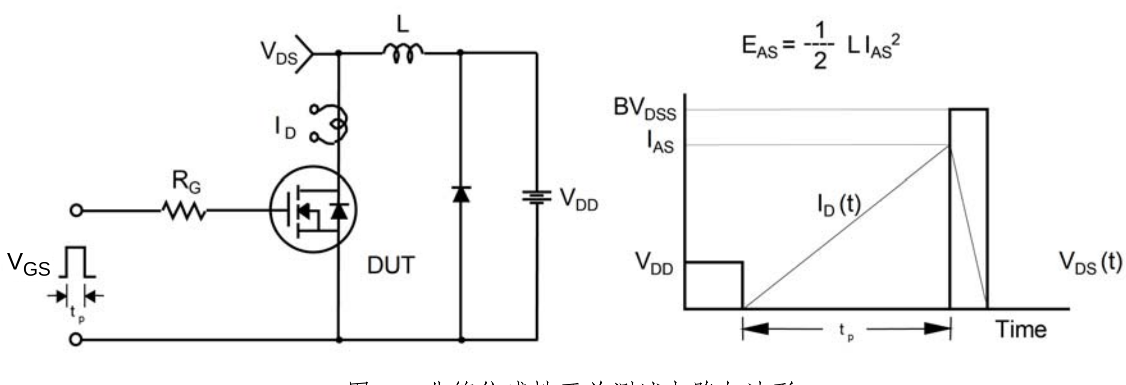


图 **14.** 非箝位感性开关测试电路与波形

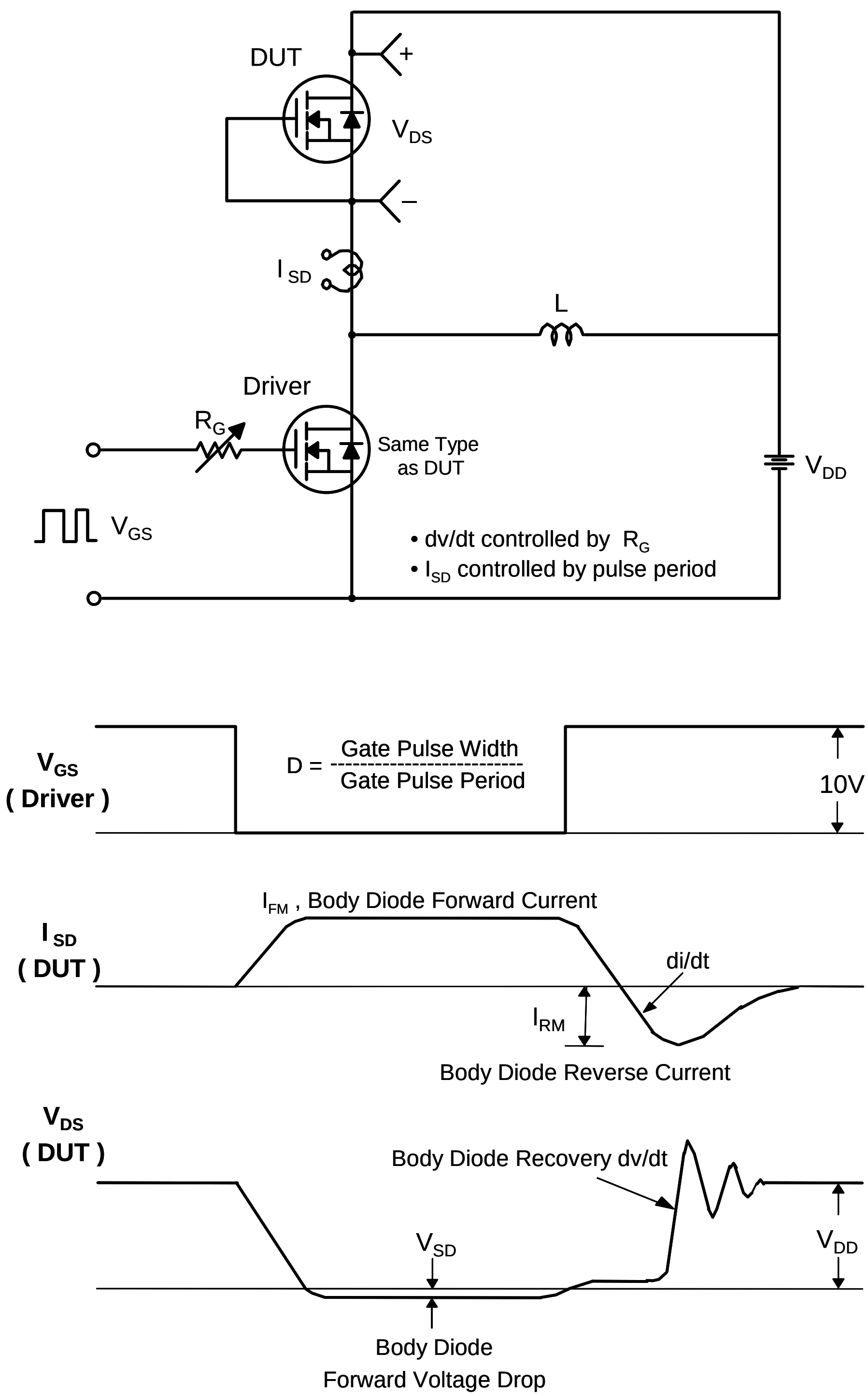


图 **15.** 峰值二极管恢复 **dv/dt** 测试电路与波形

机械尺寸

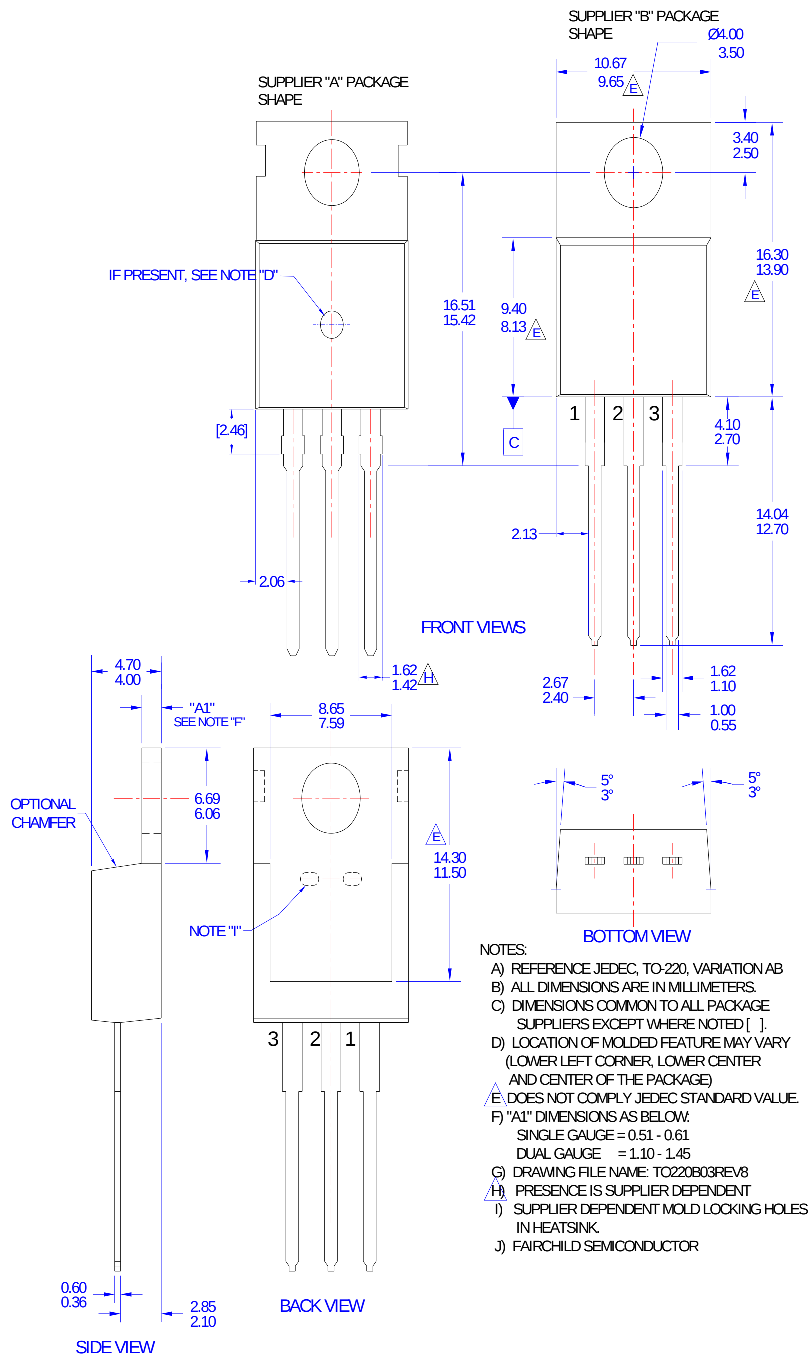


图 **16. TO-220**，模塑，**3** 引脚，**Jedec** 变量 **AB**

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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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